



# PMN30XPA

20 V, P-channel Trench MOSFET

20 April 2020

Product data sheet

## 1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in a small SOT457 (SC-74) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

## 2. Features and benefits

- Low threshold voltage
- Extended temperature range  $T_j = 175\text{ °C}$
- Very fast switching
- Trench MOSFET technology
- AEC-Q101 qualified

## 3. Applications

- Relay driver
- High-speed line driver
- High-side load switch
- Switching circuits

## 4. Quick reference data

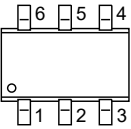
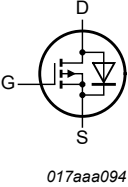
Table 1. Quick reference data

| Symbol                        | Parameter                        | Conditions                                                        | Min | Typ | Max  | Unit |
|-------------------------------|----------------------------------|-------------------------------------------------------------------|-----|-----|------|------|
| $V_{DS}$                      | drain-source voltage             | $T_j = 25\text{ °C}$                                              | -   | -   | -20  | V    |
| $V_{GS}$                      | gate-source voltage              |                                                                   | -12 | -   | 12   | V    |
| $I_D$                         | drain current                    | $V_{GS} = -4.5\text{ V}; T_{amb} = 25\text{ °C}$                  | [1] | -   | -5.2 | A    |
| <b>Static characteristics</b> |                                  |                                                                   |     |     |      |      |
| $R_{DS(on)}$                  | drain-source on-state resistance | $V_{GS} = -4.5\text{ V}; I_D = -5.2\text{ A}; T_j = 25\text{ °C}$ | -   | 30  | 38   | mΩ   |

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain  $6\text{ cm}^2$ .

5. Pinning information

Table 2. Pinning information

| Pin | Symbol | Description | Simplified outline                                                                                         | Graphic symbol                                                                                   |
|-----|--------|-------------|------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------|
| 1   | D      | drain       | <br>SC-74; TSOP6 (SOT457) | <br>017aaa094 |
| 2   | D      | drain       |                                                                                                            |                                                                                                  |
| 3   | G      | gate        |                                                                                                            |                                                                                                  |
| 4   | S      | source      |                                                                                                            |                                                                                                  |
| 5   | D      | drain       |                                                                                                            |                                                                                                  |
| 6   | D      | drain       |                                                                                                            |                                                                                                  |

6. Ordering information

Table 3. Ordering information

| Type number | Package      |                                                          |         |
|-------------|--------------|----------------------------------------------------------|---------|
|             | Name         | Description                                              | Version |
| PMN30XPA    | SC-74; TSOP6 | plastic, surface-mounted package (SC-74; TSOP6); 6 leads | SOT457  |

7. Marking

Table 4. Marking codes

| Type number | Marking code |
|-------------|--------------|
| PMN30XPA    | 3T           |

## 8. Limiting values

**Table 5. Limiting values**

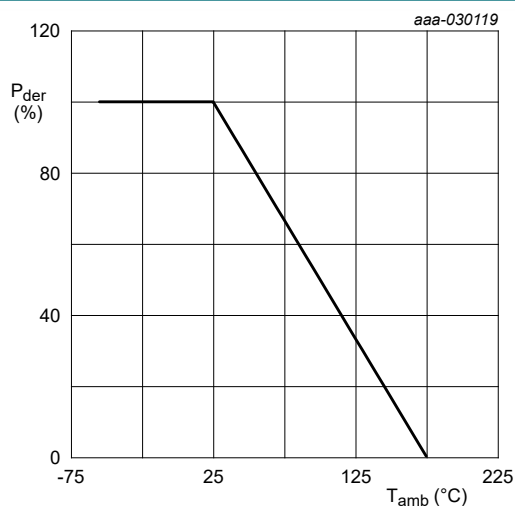
In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol                      | Parameter                                    | Conditions                                                                             |     | Min | Max  | Unit |
|-----------------------------|----------------------------------------------|----------------------------------------------------------------------------------------|-----|-----|------|------|
| V <sub>DS</sub>             | drain-source voltage                         | T <sub>j</sub> = 25 °C                                                                 |     | -   | -20  | V    |
| V <sub>GS</sub>             | gate-source voltage                          |                                                                                        |     | -12 | 12   | V    |
| I <sub>D</sub>              | drain current                                | V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 25 °C                                     | [1] | -   | -5.2 | A    |
|                             |                                              | V <sub>GS</sub> = -4.5 V; T <sub>amb</sub> = 100 °C                                    | [1] | -   | -3.3 | A    |
| I <sub>DM</sub>             | peak drain current                           | T <sub>amb</sub> = 25 °C; single pulse; t <sub>p</sub> ≤ 10 μs                         |     | -   | -21  | A    |
| P <sub>tot</sub>            | total power dissipation                      | T <sub>amb</sub> = 25 °C                                                               | [2] | -   | 660  | mW   |
|                             |                                              |                                                                                        | [1] | -   | 1.7  | W    |
|                             |                                              | T <sub>sp</sub> = 25 °C                                                                |     | -   | 7.5  | W    |
| T <sub>j</sub>              | junction temperature                         |                                                                                        |     | -55 | 175  | °C   |
| T <sub>amb</sub>            | ambient temperature                          |                                                                                        |     | -55 | 175  | °C   |
| T <sub>stg</sub>            | storage temperature                          |                                                                                        |     | -65 | 175  | °C   |
| <b>Source-drain diode</b>   |                                              |                                                                                        |     |     |      |      |
| I <sub>S</sub>              | source current                               | T <sub>amb</sub> = 25 °C                                                               | [1] | -   | -1.7 | A    |
| <b>ESD maximum rating</b>   |                                              |                                                                                        |     |     |      |      |
| V <sub>ESD</sub>            | electrostatic discharge voltage              | HBM                                                                                    | [3] | -   | 500  | V    |
| <b>Avalanche ruggedness</b> |                                              |                                                                                        |     |     |      |      |
| E <sub>DS(AL)S</sub>        | non-repetitive drain-source avalanche energy | T <sub>j(initial)</sub> = 25 °C; I <sub>D</sub> = -1.5 A; DUT in avalanche (unclamped) |     | -   | 15.5 | mJ   |

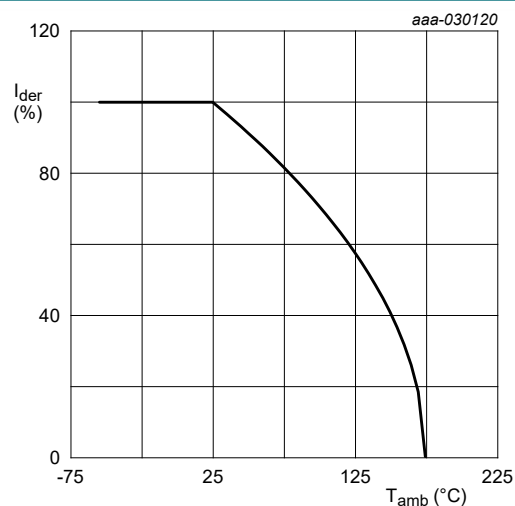
[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.

[2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[3] Measured between all pins.



**Fig. 1. Normalized total power dissipation as a function of ambient temperature**



**Fig. 2. Normalized continuous drain current as a function of ambient temperature**

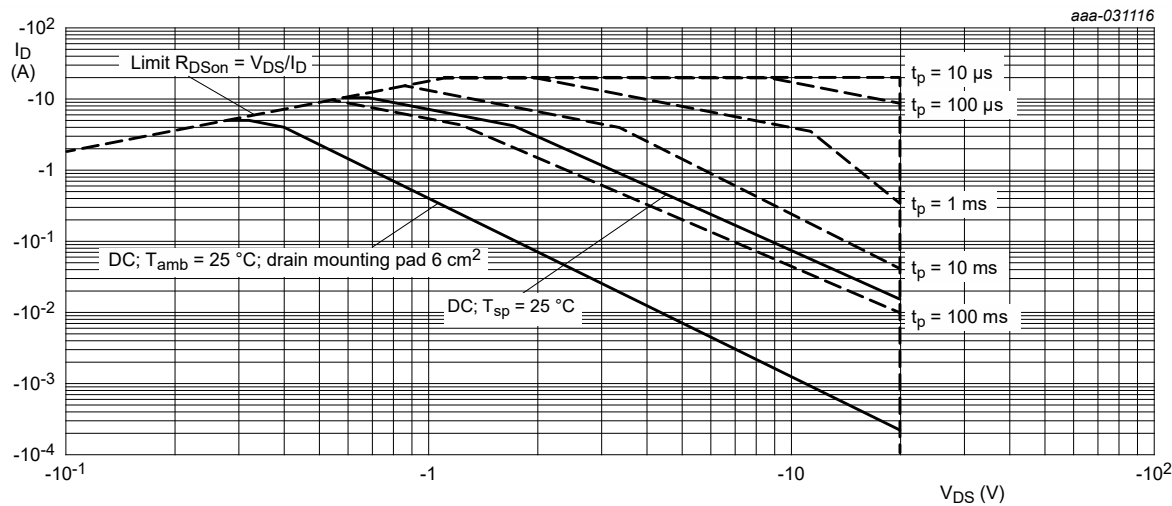


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

| Symbol         | Parameter                                        | Conditions  |     | Min | Typ | Max | Unit |
|----------------|--------------------------------------------------|-------------|-----|-----|-----|-----|------|
| $R_{th(j-a)}$  | thermal resistance from junction to ambient      | in free air | [1] | -   | 195 | 225 | K/W  |
|                |                                                  |             | [2] | -   | 78  | 90  | K/W  |
| $R_{th(j-sp)}$ | thermal resistance from junction to solder point |             |     | -   | 15  | 20  | K/W  |

- [1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.  
[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.

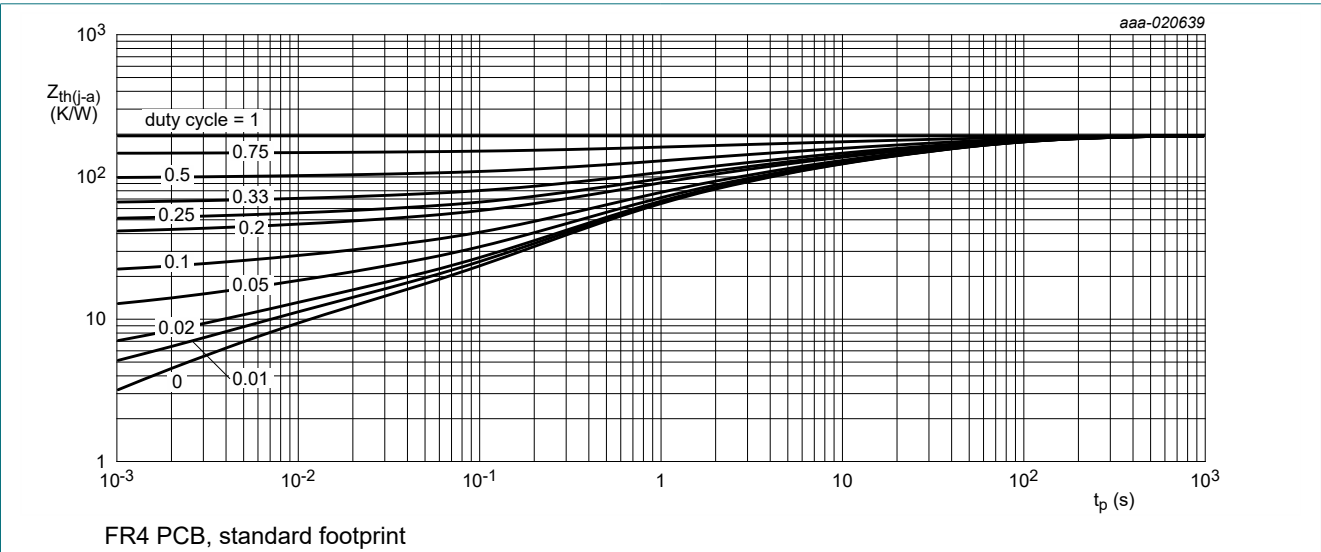


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

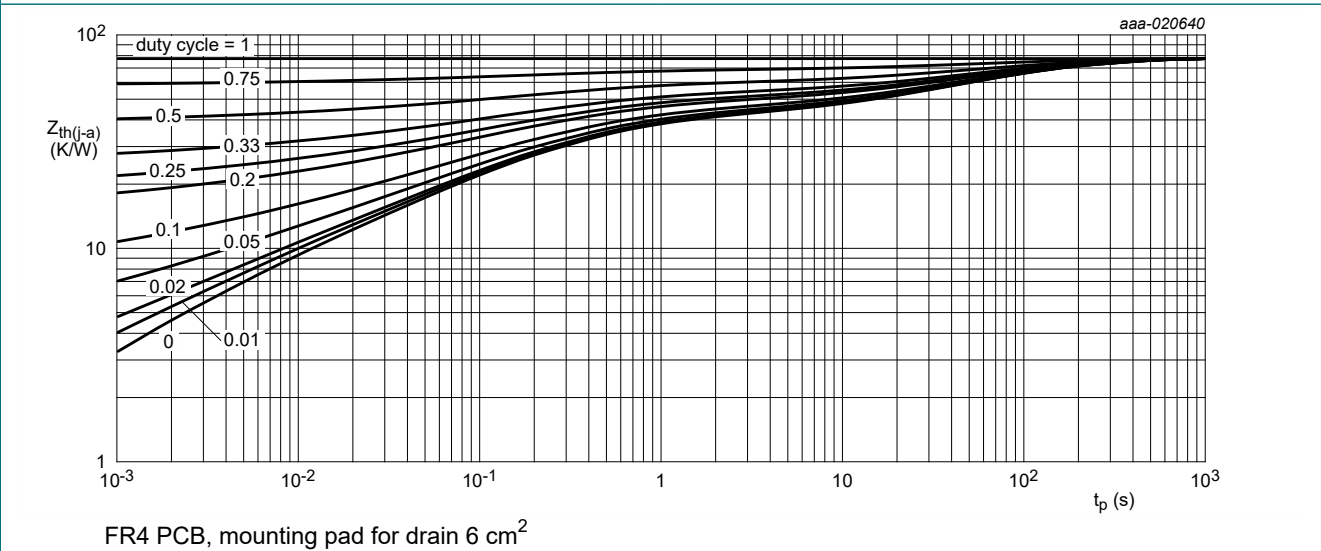


Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

## 10. Characteristics

Table 7. Characteristics

| Symbol                  | Parameter                        | Conditions                                                                                                                      |  | Min  | Typ   | Max  | Unit |
|-------------------------|----------------------------------|---------------------------------------------------------------------------------------------------------------------------------|--|------|-------|------|------|
| Static characteristics  |                                  |                                                                                                                                 |  |      |       |      |      |
| V <sub>(BR)DSS</sub>    | drain-source breakdown voltage   | I <sub>D</sub> = -250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                         |  | -20  | -     | -    | V    |
| V <sub>GSth</sub>       | gate-source threshold voltage    | I <sub>D</sub> = -250 μA; V <sub>DS</sub> = V <sub>GS</sub> ; T <sub>j</sub> = 25 °C                                            |  | -0.6 | -0.95 | -1.3 | V    |
| I <sub>DSS</sub>        | drain leakage current            | V <sub>DS</sub> = -20 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                          |  | -    | -     | -1   | μA   |
| I <sub>GSS</sub>        | gate leakage current             | V <sub>GS</sub> = -12 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                          |  | -    | -     | -100 | nA   |
|                         |                                  | V <sub>GS</sub> = 12 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                           |  | -    | -     | 100  | nA   |
| R <sub>DSon</sub>       | drain-source on-state resistance | V <sub>GS</sub> = -8 V; I <sub>D</sub> = -5.2 A; T <sub>j</sub> = 25 °C                                                         |  | -    | 25    | 33   | mΩ   |
|                         |                                  | V <sub>GS</sub> = -8 V; I <sub>D</sub> = -5.2 A; T <sub>j</sub> = 175 °C                                                        |  | -    | 40    | 53   | mΩ   |
|                         |                                  | V <sub>GS</sub> = -4.5 V; I <sub>D</sub> = -5.2 A; T <sub>j</sub> = 25 °C                                                       |  | -    | 30    | 38   | mΩ   |
|                         |                                  | V <sub>GS</sub> = -2.5 V; I <sub>D</sub> = -3 A; T <sub>j</sub> = 25 °C                                                         |  | -    | 45    | 62   | mΩ   |
| g <sub>fs</sub>         | forward transconductance         | V <sub>DS</sub> = -10 V; I <sub>D</sub> = -4.9 A; T <sub>j</sub> = 25 °C                                                        |  | -    | 18    | -    | S    |
| R <sub>G</sub>          | gate resistance                  | f = 1 MHz                                                                                                                       |  | -    | 6     | -    | Ω    |
| Dynamic characteristics |                                  |                                                                                                                                 |  |      |       |      |      |
| Q <sub>G(tot)</sub>     | total gate charge                | V <sub>DS</sub> = -10 V; I <sub>D</sub> = -5 A; V <sub>GS</sub> = -4.5 V; T <sub>j</sub> = 25 °C                                |  | -    | 11    | 16   | nC   |
| Q <sub>GS</sub>         | gate-source charge               |                                                                                                                                 |  | -    | 1.9   | -    | nC   |
| Q <sub>GD</sub>         | gate-drain charge                |                                                                                                                                 |  | -    | 3.4   | -    | nC   |
| C <sub>iss</sub>        | input capacitance                | V <sub>DS</sub> = -10 V; f = 1 MHz; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C                                               |  | -    | 1039  | -    | pF   |
| C <sub>oss</sub>        | output capacitance               |                                                                                                                                 |  | -    | 124   | -    | pF   |
| C <sub>rss</sub>        | reverse transfer capacitance     |                                                                                                                                 |  | -    | 110   | -    | pF   |
| t <sub>d(on)</sub>      | turn-on delay time               | V <sub>DS</sub> = -10 V; I <sub>D</sub> = -5 A; V <sub>GS</sub> = -4.5 V; R <sub>G(ext)</sub> = 6 Ω; T <sub>j</sub> = 25 °C     |  | -    | 8     | -    | ns   |
| t <sub>r</sub>          | rise time                        |                                                                                                                                 |  | -    | 30    | -    | ns   |
| t <sub>d(off)</sub>     | turn-off delay time              |                                                                                                                                 |  | -    | 40    | -    | ns   |
| t <sub>f</sub>          | fall time                        |                                                                                                                                 |  | -    | 23    | -    | ns   |
| Source-drain diode      |                                  |                                                                                                                                 |  |      |       |      |      |
| V <sub>SD</sub>         | source-drain voltage             | I <sub>S</sub> = -1.7 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C                                                          |  | -    | -0.8  | -1.2 | V    |
| t <sub>rr</sub>         | reverse recovery time            | I <sub>S</sub> = -1.5 A; dI <sub>S</sub> /dt = 100 A/μs; V <sub>GS</sub> = 0 V; V <sub>DS</sub> = -10 V; T <sub>j</sub> = 25 °C |  | -    | 13    | -    | ns   |
| Q <sub>r</sub>          | recovered charge                 |                                                                                                                                 |  | -    | 3     | -    | nC   |

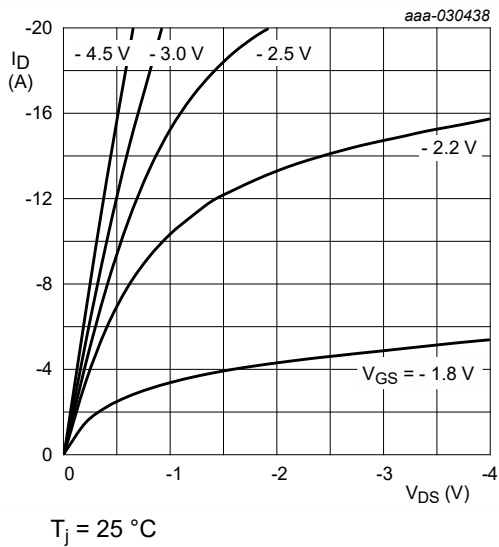


Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values

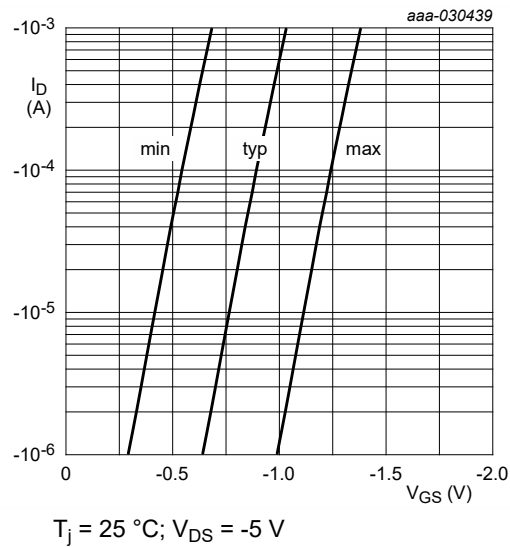


Fig. 7. Subthreshold drain current as a function of gate-source voltage

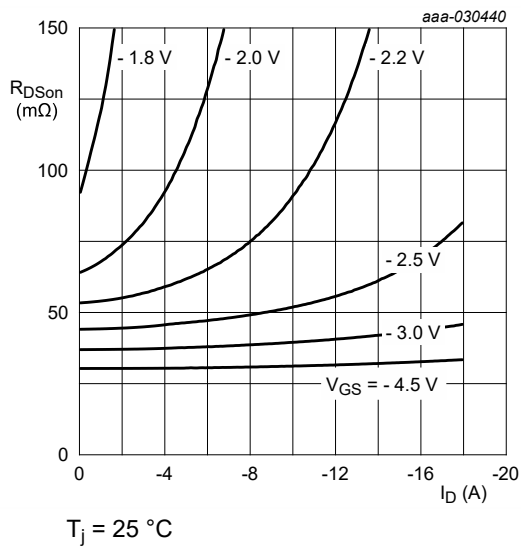


Fig. 8. Drain-source on-state resistance as a function of drain current; typical values

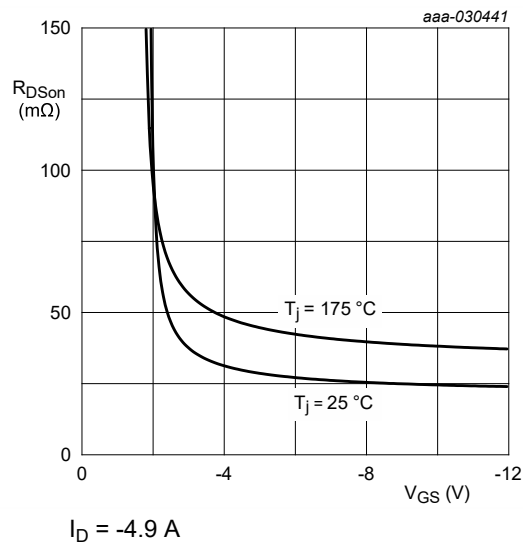


Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values

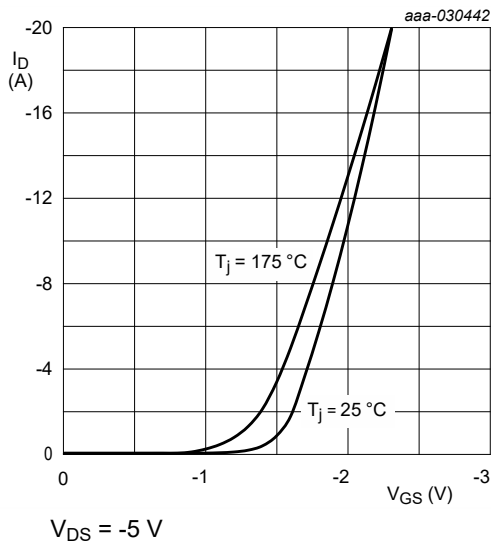


Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

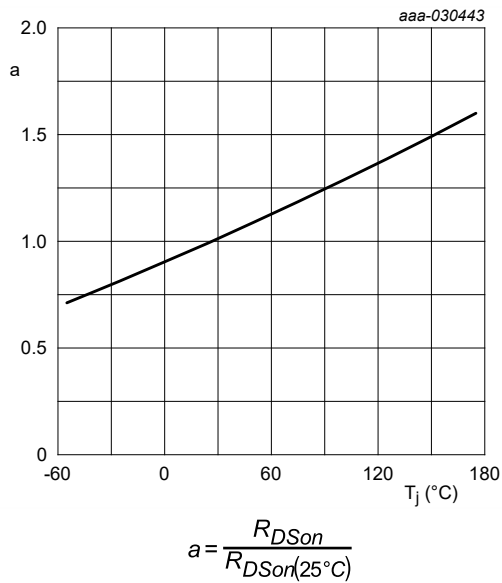


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

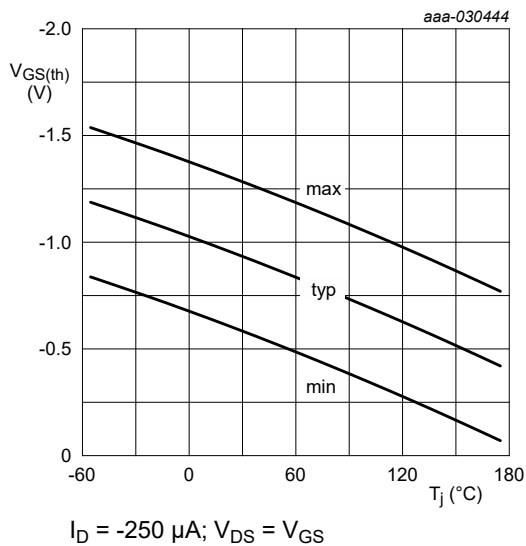


Fig. 12. Gate-source threshold voltage as a function of junction temperature

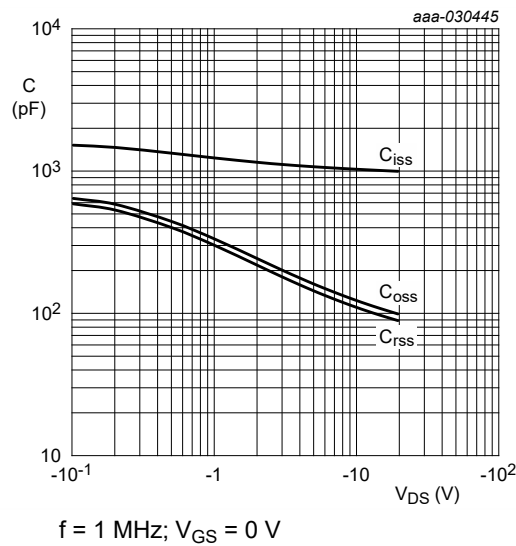


Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

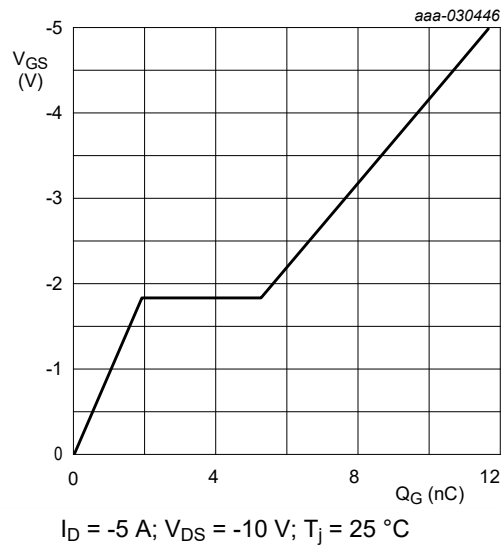


Fig. 14. Gate-source voltage as a function of gate charge; typical values

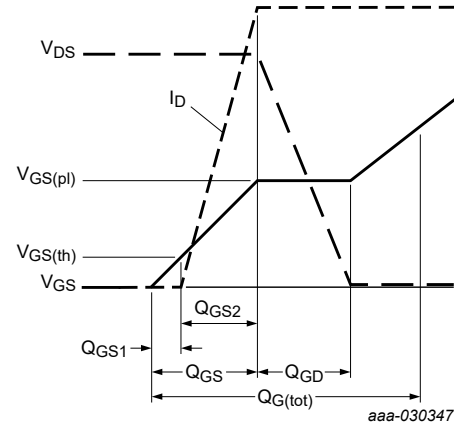


Fig. 15. Gate charge waveform definitions

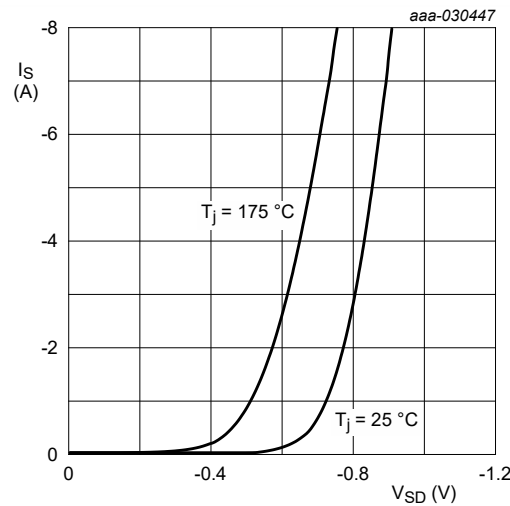


Fig. 16. Source current as a function of source-drain voltage; typical values

## 11. Test information

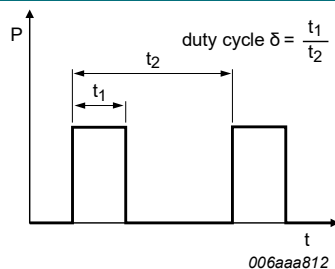


Fig. 17. Duty cycle definition

### Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard *Q101 - Stress test qualification for discrete semiconductors*, and is suitable for use in automotive applications.

12. Package outline

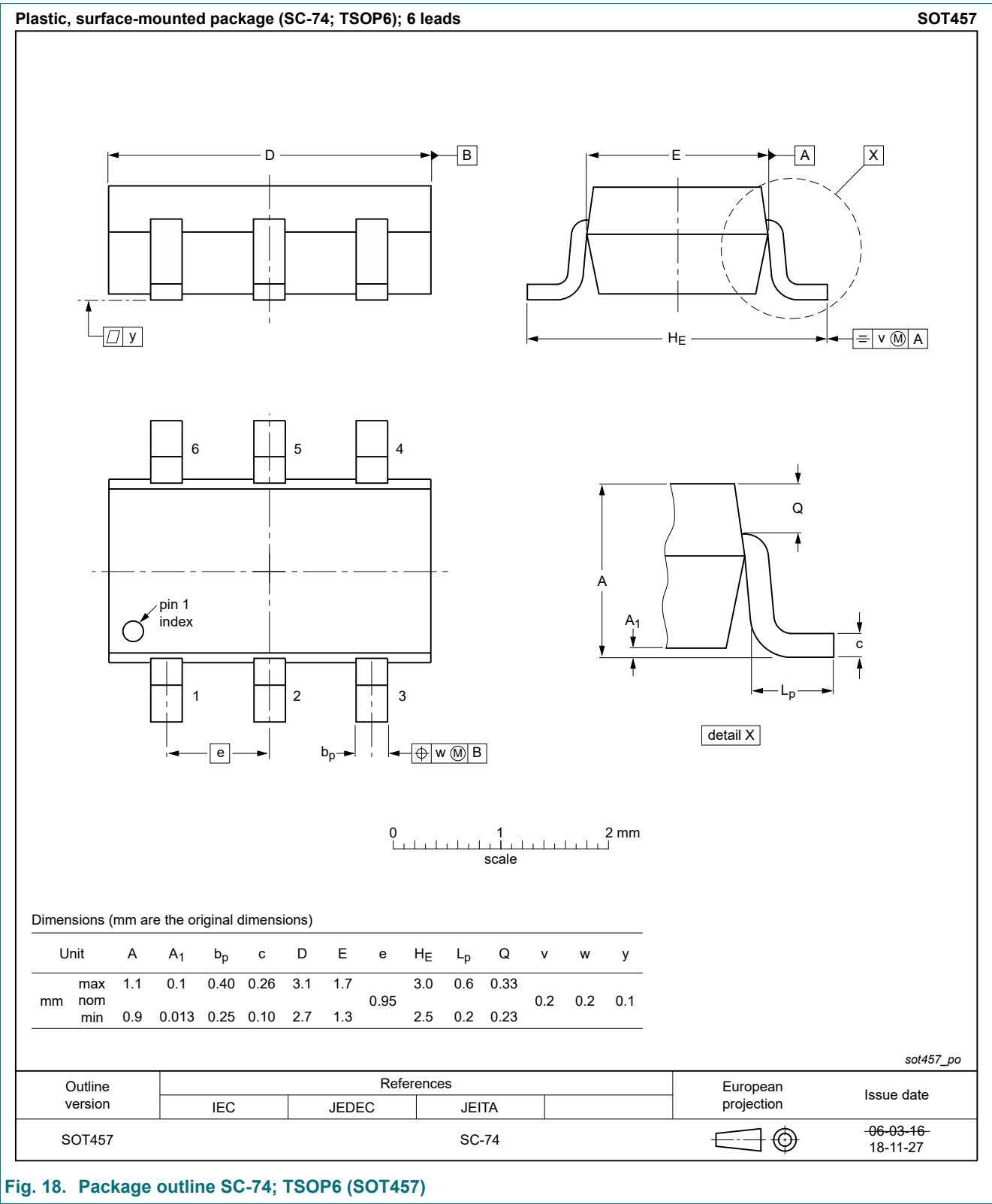
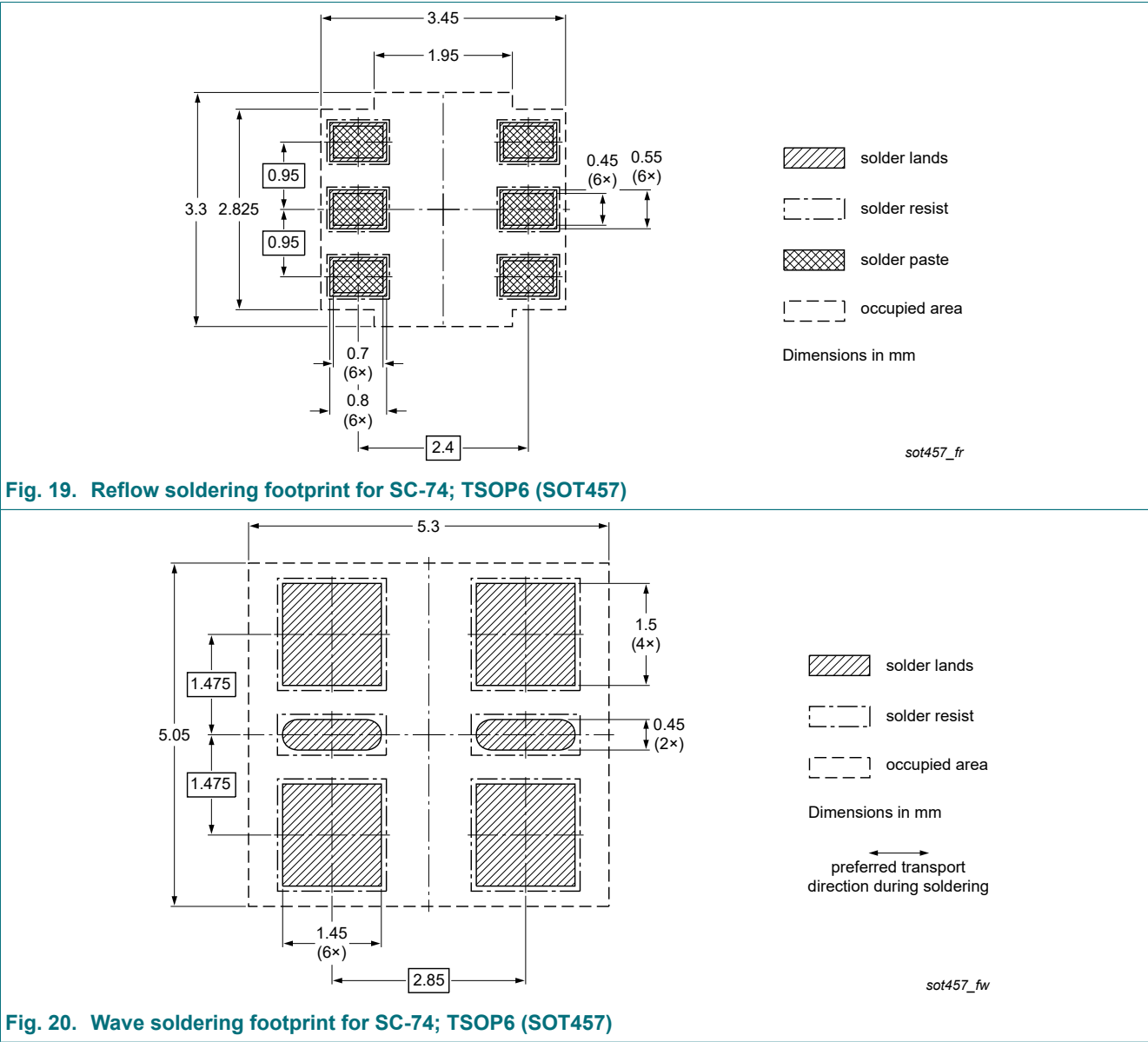


Fig. 18. Package outline SC-74; TSOP6 (SOT457)

13. Soldering



14. Revision history

Table 8. Revision history

| Data sheet ID | Release date | Data sheet status  | Change notice | Supersedes |
|---------------|--------------|--------------------|---------------|------------|
| PMN30XPA v.1  | 20200420     | Product data sheet | -             | -          |

## 15. Legal information

### Data sheet status

| Document status<br>[1][2]      | Product status [3] | Definition                                                                            |
|--------------------------------|--------------------|---------------------------------------------------------------------------------------|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification      | This document contains data from the preliminary specification.                       |
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